

SPECIFICATIONS

CUSTOMER: Shenzhen pengban Xingye Technology Co., Ltd

DESCRIPTION:

CUSTOMER PART No: Bluetooth antenna

OUR MODEL NO: PBX5016DA02

DATE: 2020/12/22

PBX5016DA02 Specification

Operating Temp. : -40°C~+85°C

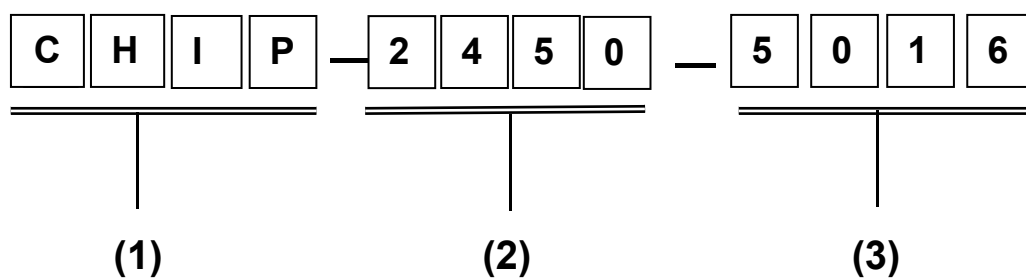
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

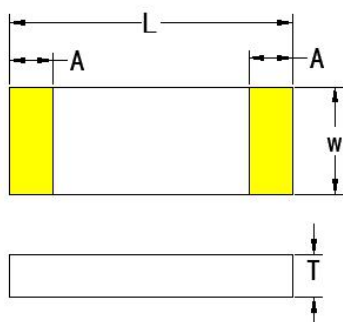
- Bluetooth, Wireless LAN, Mobile TV
- Home RF system, etc

3. PRODUCT IDENTIFICATION



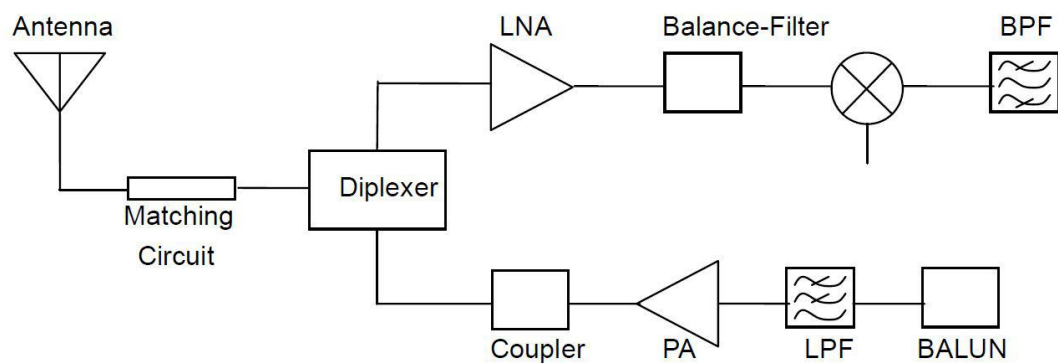
- (1) Product type: Ceramic antenna
(2) Center Frequency: 2450MHz
(3) External Dimensions (L×W) (mm): 5.0*1.6

4. SHAPE AND DIMENSIONS:



Unit:mm	L	W	A	T
CHIP-5016	5.0±0.1	1.6±0.1	0.45±0.1	0.85±0.1

APPLICATION GUIDE



5. SPECIFICATIONS:

Test Project	Result
Operating Frequency	2400-2500MHz
Polarization mode	Antenna polarization
Antenna gain	2.73dBi
Efficient	67.16%
Impedance	50Ω
Maximum power	5W

* Test condition: Test board size 86*50 mm

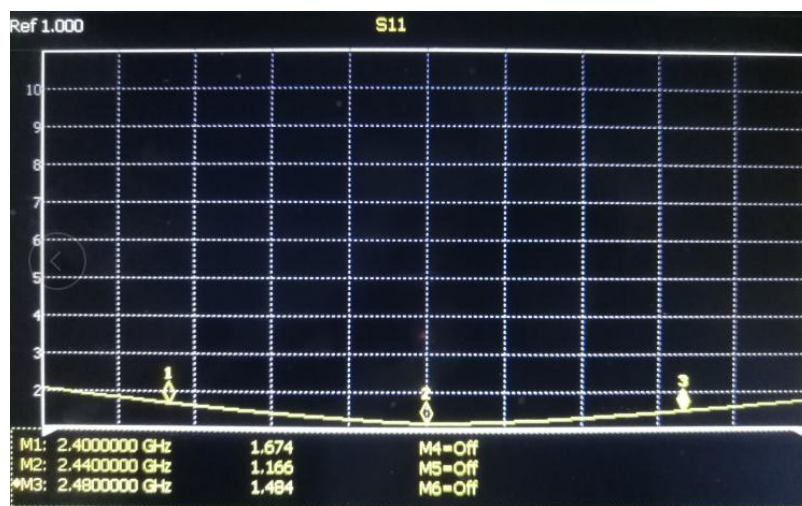
Matching circuit: Pi matching circuit will be required

6. Electrical Characteristics :





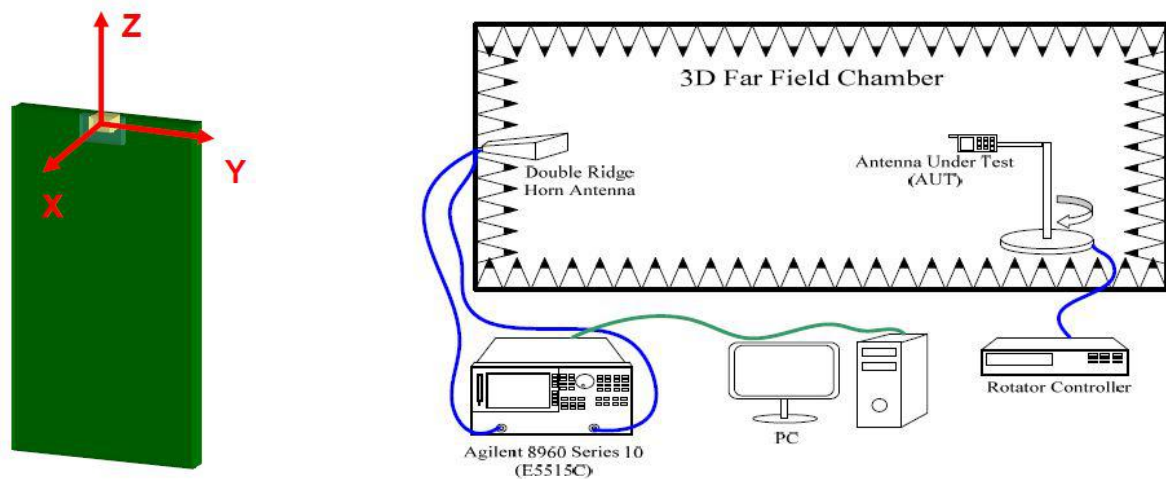
SWR



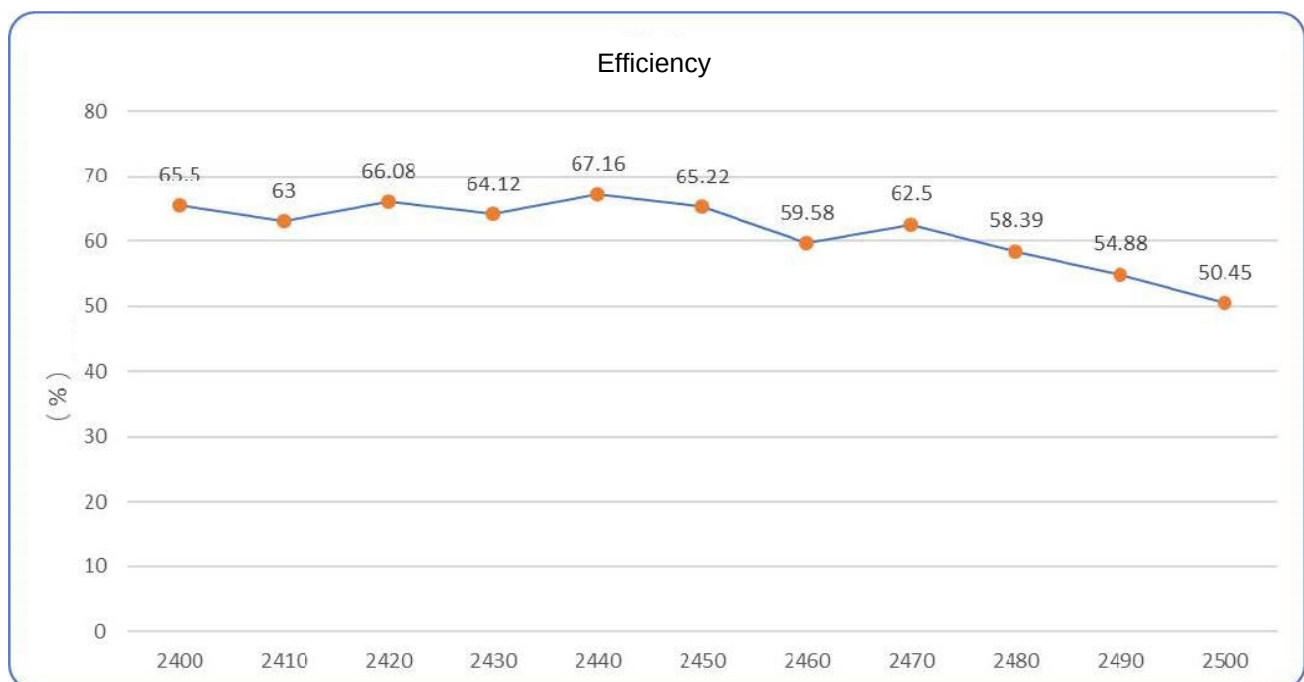
Mark	Frequency	VSWR
1	2400 MHz	1.674
2	2440 MHz	1.166
3	2480 MHz	1.484

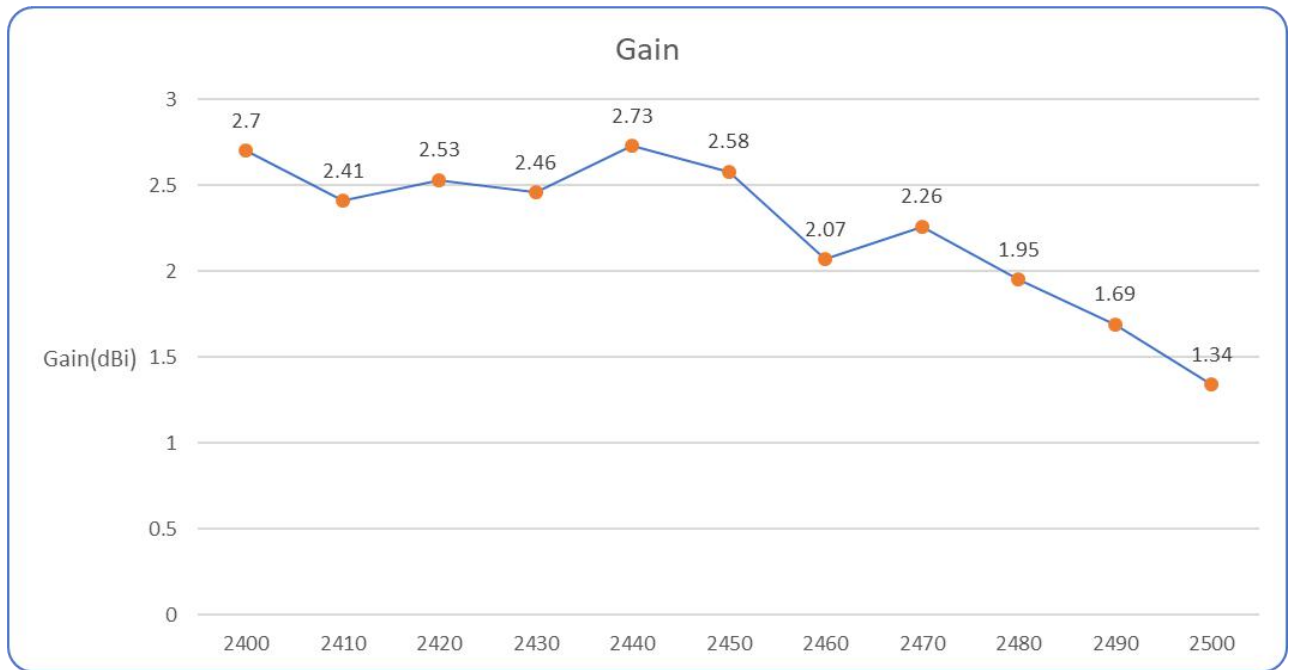
Radiation Pattern

The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.



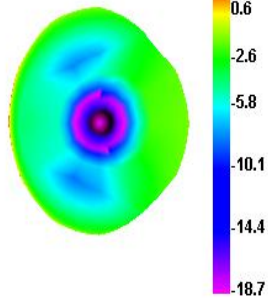
Efficiency



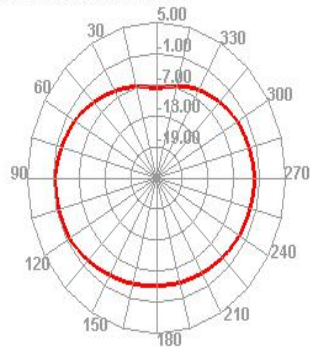


© **3D Gain Pattern (2400 MHz)**

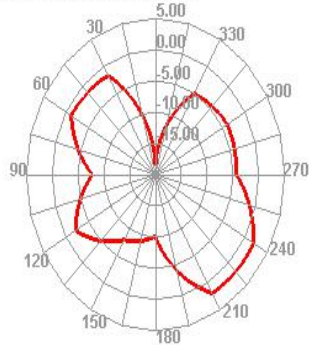
2400.000MHz



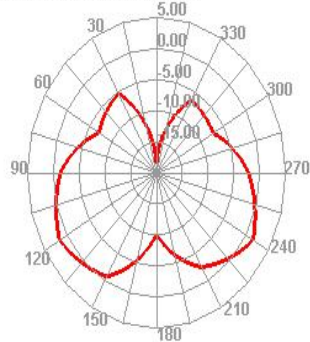
2400.000MHz H



2400.000MHz E1

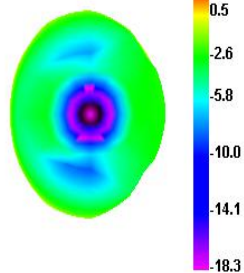


2400.000MHz E2

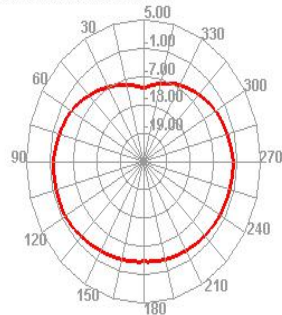


◎ 3D Gain Pattern (2450 MHz)

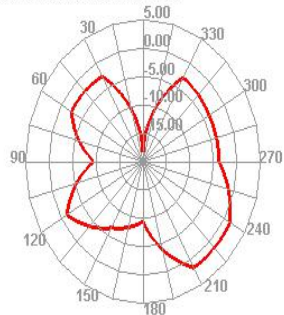
2450.000MHz



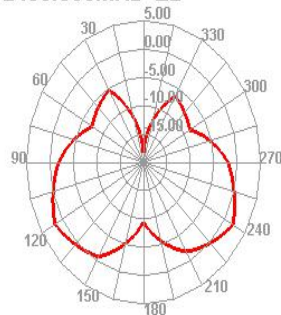
2450.000MHz H



2450.000MHz E1

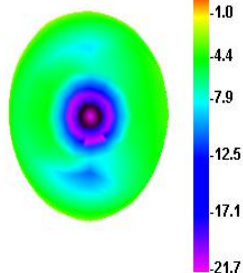


2450.000MHz E2

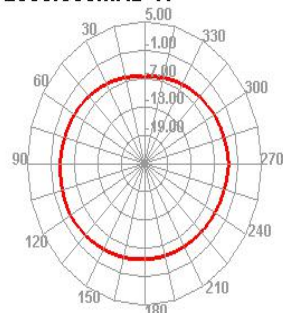


◎ 3D Gain Pattern (2500 MHz)

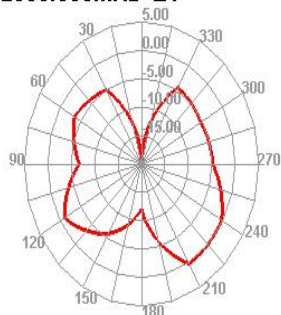
2500.000MHz



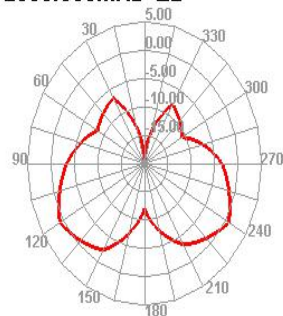
2500.000MHz H



2500.000MHz E1



2500.000MHz E2



7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at $-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$, 2. Convert to $+105^{\circ}\text{C}$ (5 minutes) 3. 30 ± 3 minutes at $+105^{\circ}\text{C}\pm 5^{\circ}\text{C}$, 4. Convert to -40°C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm 5^{\circ}\text{C}$ 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: $150^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: $-40^{\circ}\text{C}\pm 5^{\circ}\text{C}$ 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : $260\pm 5^{\circ}\text{C}$ 2. Bathing time: 10 ± 1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm 5^{\circ}\text{C}$ for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0\sim 30^{\circ}\text{C}$ and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

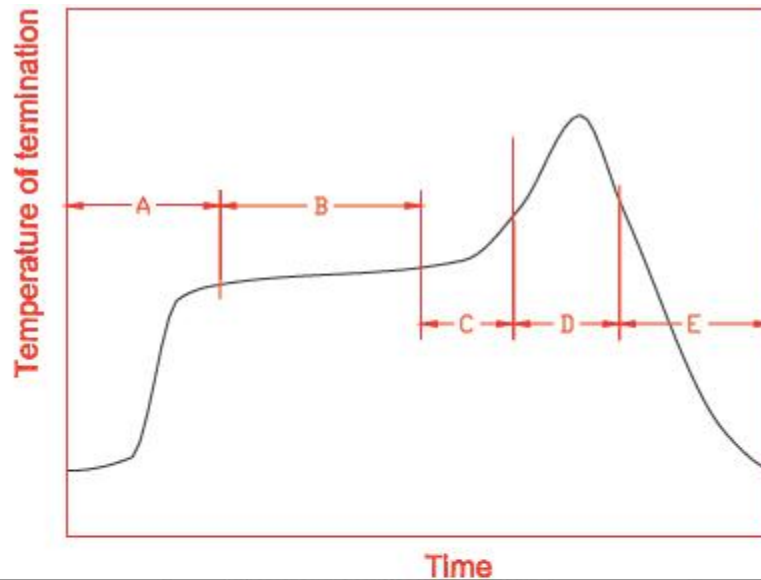
(b) On board:

The temperature should be within $-40\sim 85^{\circ}\text{C}$ and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40°C to $+105^{\circ}\text{C}$.

8. Recommended Reflow Soldering



A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
B	Preheating	140°C to 160°C	60s to 120s
C	2 nd rising temperature	Preheating to 200°C	20s to 40s
D	Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	1°C/s ~ 4°C/s

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

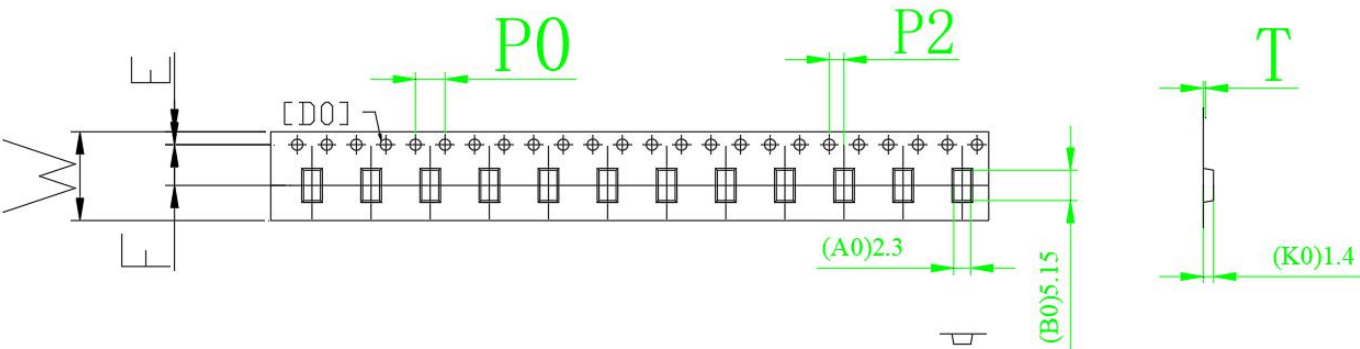
- (a) The tip temperature must be less than 350°C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

9. Taping Package and Label Marking: (unit: mm)

(1) Quantity/Reel: 4000pcs/Reel



ITEM	W	A0	B0	K0	K1	P	F	E	S0	D0	D1	P0	P2	T
DIM	12.00	2.30	5.15	1.40	0.00	8.00	5.50	1.75	52.40	1.50	0.00	4.00	2.00	0.30